

Part Number: XZFBB78W

3.2x2.4mm SMD CHIP LED LAMP

Features

• Ideal for indication light on hand held products

• Long life and robust package

• Variety of lens types and color choices available

ullet Package : 1500pcs / reel

• Moisture sensitivity level : level 3

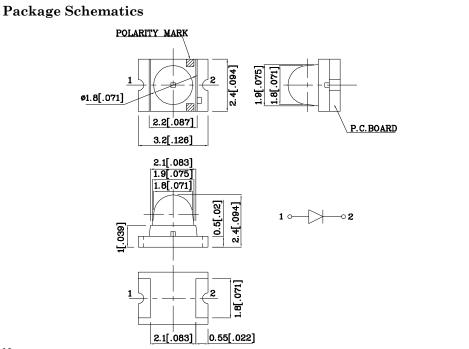
• RoHS compliant







ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



Notes

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	FBB (InGaN)	Unit		
Reverse Voltage	$V_{\rm R}$	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	100	mA	
Power Dissipation	PD	120	mW	
perating Temperature T _A		-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85	C	
Electrostatic Discharge Threshold (HBM)	250	V		

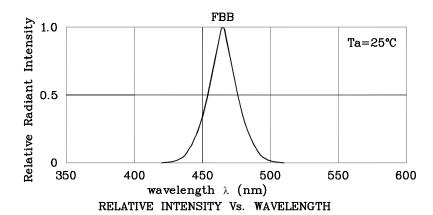
Operating Characteristics (T _A =25°C)		FBB (InGaN)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	3.3	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	4	V	
Reverse Current (Max.) $(V_R=5V)$	I_R	50	uA	
Wavelength of Peak Emission (Typ.) $(I_F=20 \text{mA})$	λΡ	465	nm	
Wavelength of Dominant Emission (Typ.) $(I_F=20\text{mA})$	λD	470	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$\triangle \lambda$	22	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	100	рF	

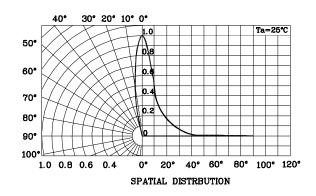
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} \text{Luminous} \\ \text{Intensity} \\ \text{(I}_{\text{F}}\text{=}20\text{mA)} \\ \text{mcd} \end{array}$		Wavelength nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZFBB78W	Blue	InGaN	Water Clear	1800	1990	465	20°

Mar 23,2011 XDSB5708 V1 Layout: Maggie L.

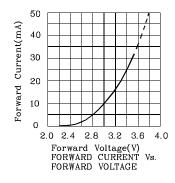


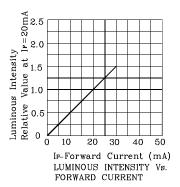


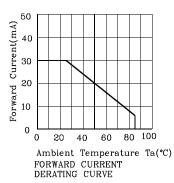


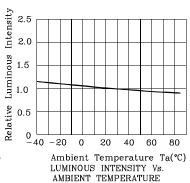


♦ FBB



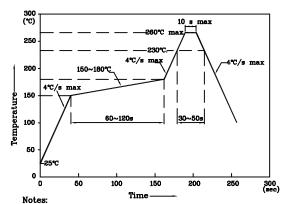






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

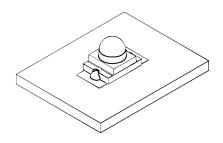


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

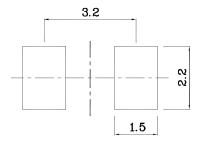




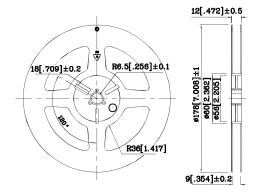
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



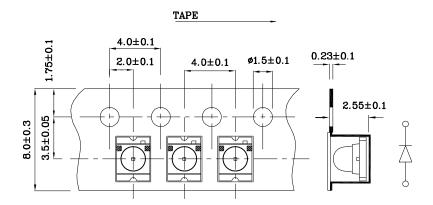
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

Mar 23,2011

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PACKING & LABEL SPECIFICATIONS

